F Control and test procedures according to DIN IEC 60512-5		1	2	۲ - ۲	1	1		Г	
			ζ	3		4		5	Ь
							•		
$ \frac{ }{ } \frac{ }{ } $								Recommended configuration	a of plated through holes for press-in termination
$ \frac{ }{ } \frac{ }{ } $		HARTING DIN Sinna	al male connector	r strainht - T	HR ([T >4(HS./		
$ \frac{\frac{1}{1000} \frac{1}{1000} \frac{1}{1$	А			Shi digini - I			plient V	In addition to the hot-air-	level (HAL), other PCB surfaces are getting more important.
$\frac{1}{1000} \frac{1}{1000} \frac{1}{1000$								Due to their different pro	operties – such as mechanical strength and coefficient of
$ \frac{1}{2} \frac{1}{1} 1$								friction - we recommend t	he following configuration of PCB through holes.
$ \left[\begin{array}{c c c c c c } \hline \hline c \\ c \\$					-			• drilled H	nole Ø
Internal Internal Internal I		General information						.	Cu min. 25µm
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $									
$ \left[\begin{array}{c c c } \hline \hline \\ $				types: Q, 2Q, 3Q, R, 1	2R, 3R, R (HE11) male			. F	
$ \frac{1}{1000} \frac{1}{10000000000000000000000000000000000$		No. of contacts							
$ \left[\begin{array}{c c c c } \hline \mathbf{E} & \frac{\mathbf{E} \cdot \mathbf{E} \cdot \mathbf{E} \cdot \mathbf{E} & \frac{\mathbf{E} \cdot \mathbf{E} \cdot \mathbf{E} \cdot \mathbf{E} \cdot \mathbf{E} & \frac{\mathbf{E} \cdot $		Contact spacing	2,54mm						
B Interview a HO 2017 to definit (up and the particular of the parties of the partin of the partis of the particular of the partin of t		Test voltage	1000V						
$ \left[\begin{array}{c c c } \hline \mathbf{e} & \frac{\mathbf{e} \cdot \mathbf{e} \cdot e$		Contact resistance	≤ 15mOhm						
$ \left[\begin{array}{c c c } \hline \mathbf{e} & \frac{\mathbf{e} \cdot \mathbf{e} \cdot e$		Insulation resistance	≥ 10 ¹² 0hm					finishe	ed hole Ø
Interface large Transient indings Transient india i		Working current	max. 2A at 20°C (se	e derating diagram)				·	
$\frac{1}{1} \frac{1}{1} \frac{1}$	В		-55°C +125°C	<u>-</u>					plating (e.g. Sn)
$ \frac{ }{ } \frac{ }{ } \frac{ }{ } \frac{ }{ } \frac{ }{ } \frac{ }{ } \frac{ }{ } \frac{ }{ } \frac{ }{ } $		lemperature range	max. 15s at 240°C f	or reflow soldering					
Descend a recognition Instrume 1 12-54-12 B0 12-54-		Termination terboology							
Image: The anti-Virtunal stream and virtunal stream and the stream and virtunal virtunal virtunal virtunal vi									
$ \left \begin{array}{c c c c c c c c c c c c c c c c c c c $			· · ·	18-pole < 15N	,			·	
Particle 2016 Notation 2010 Hilding colds acc in performance level, see table below. V. No. 1000 Hilding colds 1000 Hilding c		Incontion and withdrawal force	I.	1				Assembly instructions	
Image optiming Bit is the participation base Press of the This designed for this, fraghters also there also there also the also t			I	1					
It find C102000 INDES Control of the second								. It is highly recommended t	o use HARTING press-in tools to ensure a reliable press-in
Biol Solution Yes Horizon Yes Horizon No Hardian PCI intercolating gass The reference 1200 Conv mutual columnet gass The reference 1200 Convertion and the columnet metal of the restrict is columnet and the columnet metal of the restrict is columnet and the columnet metal of the restrict is columnet and the columnet metal of the restrict is columnet and the columnet metal of the restrict is columnet and the columnet metal of the restrict is columnet and the columnet metal of the restrict is columnet and the columnet metal of the restrict is columnet and the restrict is				level, see fable below				Please refer to the catalo	igue for tools, machines and further information about the p
Interface Tea Maximum				-		-			
Image: Supprox No Image: Supprox									
$ \begin{array}{c c c c c c } \hline \hline$								THR (Through Hole Reflow) connectors are designed to be used in a reflow over toget
C Indiate material State of the results in solar pack of the results of the results of the pack of th		Hot plugging	No					In this process, called as	well "Pin in Hole Intrusive Reflow", the connectors are inser
Image: Proteined Encode F1 Observation Encode F1 Observation Encode F1 Observation Encode F1 Observation Here we graps acc. EC 6064-1 III 400 ± C11 ± 6001 Here we graps acc. EC 6064-1 III 400 ± C11 ± 6001 Here we graps acc. EC 6064-1 III 400 ± C11 ± 6001 Here we graps acc. EC 6064-1 III 400 ± C11 ± 6001 III observation III observation III observation IIII observation III observation IIIII observa	ſ							component mounting.	
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Cover a struit course, cover deviations and species permittee BL disalifiation U.S. 49-70 Method propare, Eff 6684-1 U.G00 a CT - 500 Method propare, Eff 6684-1 U.G00 a CT - 500 Extent attribut D Extent attribut D Extent attribut D Extent attribut D Printing termination zone Science NL for solder, NL for process, therefore the quality of the attribut service in the solder to a point the point attribut service in the solder to a point the actual solder, the attribut service in the solder to a point the actual solder, the attribut service in the solder to attribut service in the solder the point attribut service in the solder to attribut service in the solder termination in the idel (Complementary act, to IEC 60603-2 act, to IEC 606		Material	PCT (thermoplastics	glass fiber reinforcement 30%)	· · · · · ·				
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F Control and test procedures according to DIN IEC 60512-5	_	Infe current carrying capacity is limited by maximum temperature							mensions in mm Scale Free size tol
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Image: Sector of the sector		The current capacity curve is valid for	continuous, non		<u></u> 1.5				
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ant.	Tin plated PCB (HAL)	Drilled hole Ø	1,15±0,025mm							
	acc. to EN 60352-5	Sn	max. 15µm							
		plated hole Ø	0,94 - 1,09mm							
	Chemical tin plated PCB	Drilled hole Ø Sn	1,15±0,025mm min. 0,8µm							
		plated hole Ø	1,00 – 1,10mm							
		Drilled hole Ø	1,15±0,025mm							
	Gold /Nickel plated PCB	Ni	3 – 7µm							
		Au	0,05 - 0,12µm							
		plated hole Ø Drilled hole Ø	1,00 - 1,10mm 1,15±0,025mm							
	Silver plated PCB	Aq	0,1 - 0,3µm							
		plated hole Ø	1,00 – 1,10mm	B						
	Copper plated	Drilled hole Ø	1,15±0,025mm							
	PCB (OSP)	plated hole Ø	1,00 – 1,10mm							
-in prod										
	s-in process.									
3	<u>. </u>									
	with other SMD (Surface Mo									
iserted	into plated through holes in	a comparable way to	conventional							
re than	1.5 millimetres after inserti	on to the och. Fach co	ntart collects solder							
ong, thi	s solder would no longer be	able to reflow back in	nto the plated through hole by							
connec	ction would suffer as a resu	ılt.								
				+						
der pad	ls (for connecting surface-m	ount components)								
older paste must be applied than traditional solder pads										
ia. For t	this purpose, it was assume	d that 50 % of the حص	ste ronsists							
3.101										
				-						
				E						
				-						
		Ref.		\mathbb{H}						
		Sub.		1						
y	Standardisation	Date	State	1						
,	HOFFMANN	2018-05-15	Final Release							
			Doc-Key / ECM-Nr.	-						
nertor strainht - LHR ((LLS400)										
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<u>A</u>3

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Как с нами связаться

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